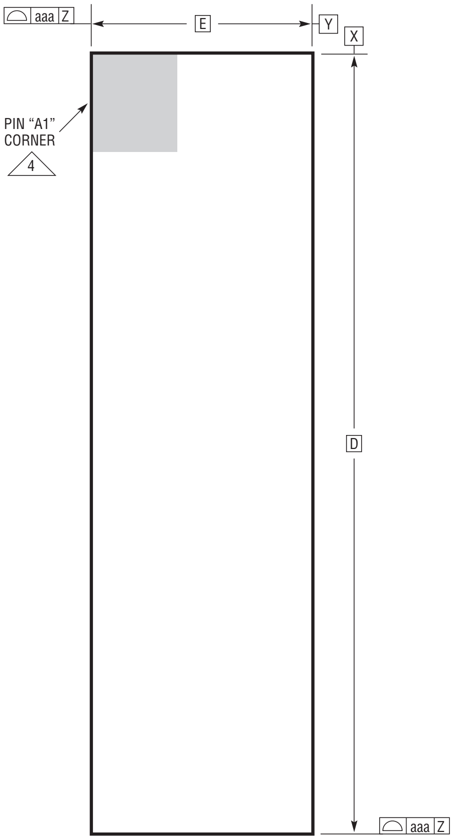
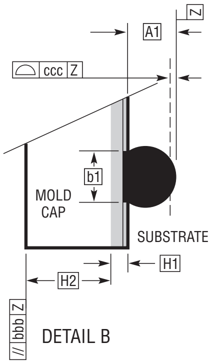
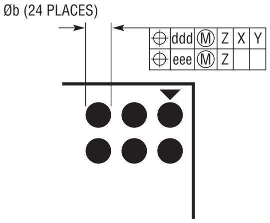
BGA Package
24-Lead (22mm × 6.25mm × 2.06mm)
(Reference LTC DWG# 05-08-1991 Rev A)



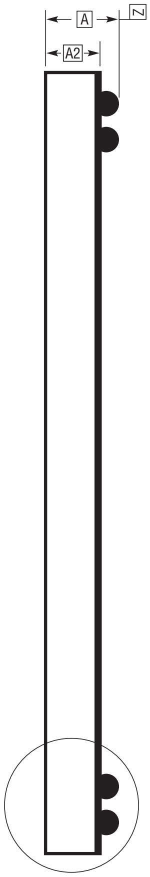
PACKAGE TOP VIEW



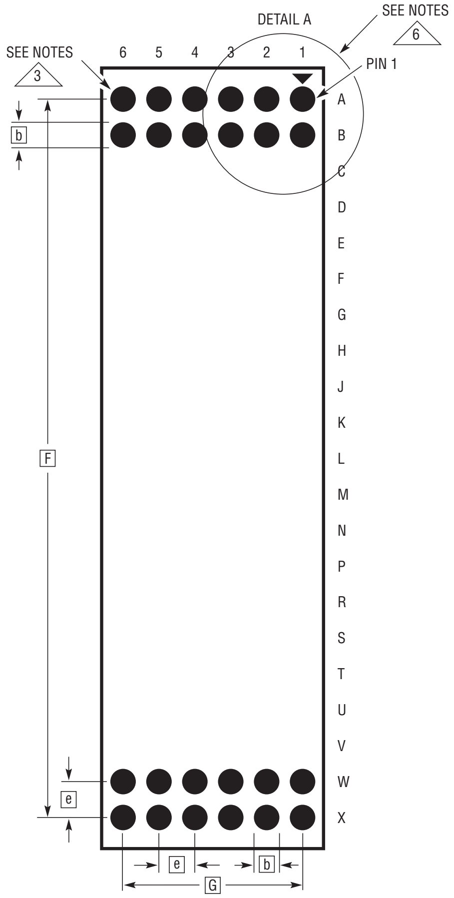
DETAIL B



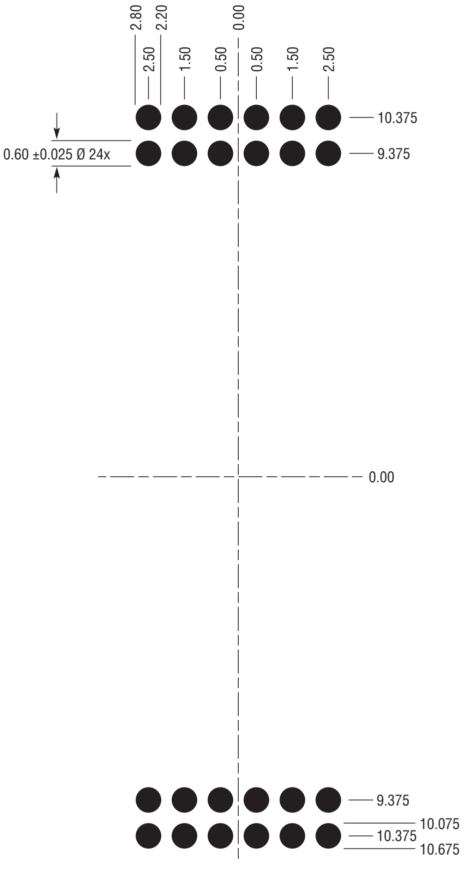
DETAIL A



DETAIL B
PACKAGE SIDE VIEW



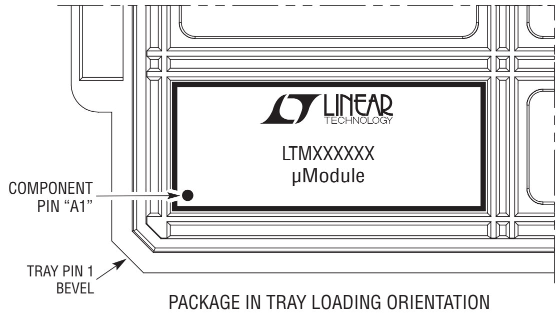
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	1.81	2.06	2.31	
A1	0.40	0.50	0.60	BALL HT
A2	1.41	1.56	1.71	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D	22.0			
E	6.25			
e	1.0			
F	20.75			
G	5.0			
H1	0.46	0.56	0.66	SUBSTRATE THK
H2	0.95	1.00	1.05	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 24				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION